

rows and aligned columns of the penetration holes, each of said penetration holes being aligned in both a row and a column of said matrix, and each row and each column of said matrix comprising at least two penetration holes;

circuit wiring disposed on both sides of said substrate; and

chip components having a height almost the same as a depth of each of said penetration holes, one of said chip components being disposed in one of said penetration holes for electrically coupling said circuit wiring disposed on both sides of said substrate.

8. (Twice Amended) A module component comprising:

a substrate made of resin having a penetration hole;

circuit wiring disposed on both sides of said substrate; and

first and second auxiliary substrates disposed such that said substrate is disposed between said first and second auxiliary substrates, and

a chip component disposed in the penetration hole, said chip component having a specified height being greater than the depth of the penetration hole and not projecting from said first and second auxiliary substrates, said chip component electrically coupling said circuit wiring disposed on both sides of said substrate,

wherein the penetration hole is formed at a position according to a matrix.

10. (Twice Amended) A module component comprising:

a substrate made of resin having a penetration hole;

circuit wiring disposed on both sides of said substrate;

a chip component having a height almost same as a depth of said penetration hole and put in the penetration hole for electrically coupling said circuit wiring disposed on both sides of said substrate;

an auxiliary substrate disposed over said substrate;

an IC chip mounted on said auxiliary substrate; and

a capacitor put in said penetration hole immediately beneath said IC chip to be coupled directly with said IC chip,

wherein the penetration hole is formed at a position according to a matrix.

12. (Twice Amended) A module component comprising:

a substrate made of resin having a penetration hole;

circuit wiring disposed on both sides of said substrate; and

a chip component having a height almost the same as a depth of said penetration hole and put in the penetration hole for electrically coupling said circuit wiring disposed on both sides of said substrate;

an auxiliary substrate disposed over said substrate;

an IC chip mounted on said auxiliary substrate; and

a ground layer disposed beneath said substrate,

wherein the penetration hole is formed at a position according to a matrix;

wherein a chip component having a specific value is accommodated to compose a desired circuit; and

wherein said IC chip is coupled directly with said ground layer.

31. (Amended) A module component comprising:

a substrate made of resin having a penetration hole;

circuit wiring disposed on both sides of said substrate;

a chip component having a height almost same as a depth of said penetration hole and put in the penetration hole for electrically coupling said circuit wiring disposed on both sides of said substrate; and

wherein the penetration hole is formed at a position according to a matrix,

wherein a chip component having a specific value is accommodated to compose a desired circuit, and

wherein the penetration hole is tapered.

32. (Amended) A module component comprising:

a substrate made of resin having a penetration hole;

circuit wiring disposed on both sides of said substrate;

a chip component having a height almost same as a depth of said penetration hole and put in the penetration hole for electrically coupling said circuit wiring disposed on both sides of said substrate; and

a ground layer disposed beneath said substrate, said ground layer being coupled with said circuit wiring disposed on a lower side of said substrate,

wherein the penetration hole is formed at a position according to a matrix, and

wherein a chip component having a specific value is accommodated to compose a desired circuit.

33. (Amended) A module component comprising:  
a substrate made of resin having a penetration hole;  
circuit wiring disposed on both sides of said substrate;  
a chip component having a height almost same as a depth of said penetration hole and put in the penetration hole for electrically coupling said circuit wiring disposed on both sides of said substrate;  
an auxiliary substrate disposed over said substrate; and  
a ground layer disposed beneath said auxiliary substrate, said ground layer being coupled with said circuit wiring disposed on a lower side of said substrate.

34. (Amended) A module component comprising:  
a substrate made of resin having a penetration hole;  
circuit wiring disposed on both sides of said substrate;  
a chip component having a height almost same as a depth of said penetration hole and put in the penetration hole for electrically coupling said circuit wiring disposed on both sides of said substrate;  
an auxiliary substrate disposed over said substrate;  
an IC chip mounted on said auxiliary substrate; and  
a ground layer disposed beneath said auxiliary substrate,